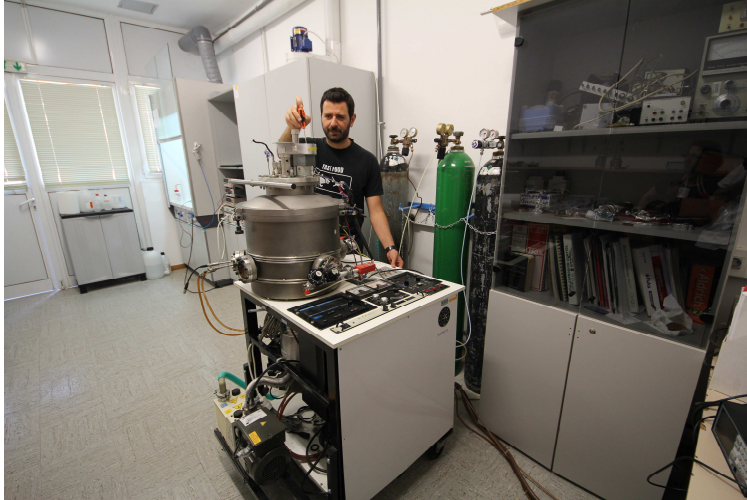


THIN FILM DEPOSITION BY SPUTTERING



MODEL: DS 210 of Oxford Applied Research

INSTALLATION PLACE: Department of Microelectronics, NCSR "Demokritos"

DESCRIPTION: Magnetron sputtering deposition system. The system contains two different guns for dc and RF sputtering deposition. Conventionally the following materials are deposited: Pt, Ti, Ni, Ag, Cu, Al, SiO₂, SiO_x, Si.

SPECIFICATIONS

1. Base pressure: $\sim 4 \times 10^{-6}$ mbar
2. Turbo pump (Varian TV551) and mechanical pump (Varian DS302)
3. Deposition rate controller (Sycon STC-200)
4. Ar plasma
5. Two guns for the simultaneous or successive deposition of two different materials
6. DC sputtering capabilities for metal deposition
7. RF sputtering capabilities for insulator deposition
8. Sample size: 3 and 4 inch wafers and small pieces

APPLICATIONS

1. Metal deposition (Al, Cu, Pt, Ti, Ni, Ag) for sensors, passive RF devices, solar cells etc.
2. Insulator deposition (SiO₂, amorphous Si, SiO) for applications in RF passive devices, sensors, light emitting devices, solar cells, etc.

CERTIFICATION/ACCREDITATION

The facility is not certified or accredited.

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